This Sheet Has Been Replaced

LEADFRAME PROCESSING FOR MOLDED PACKAGE ARRANGEMENTS

Abstract

A method for processing a leadframe for use with a molded package is disclosed. In particular, the method is suited for arrangements where direct wirebond attachment sites are exposed through the molding material. Conventional molding processes usually result in leaving a residue of molding material on the exposed wirebond sites. The invention is directed to including a protective layer of material over the wirebond locations during the leadframe plating operation. The protective layer (and any molding residue covering the protective layer) may then be removed using an etchant after the molding operation, exposing the underlying wirebond contact sites.